

## Material Content Datasheet



Performance Motion Devices

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MC2xxxIOXx.x.X.G*			
<b>Packaging Data</b>		Package Size	14mm x 20mm
		Package Type	100-pin PQFP
		Plating / Layer Composition	100% Annealed Tin (Sn)**
		Total Weight (mg)	1600
<b>Hazmat Data</b>	<b>RoHS</b>	Lead (ppm)	15
		Mercury (ppm)	15
		Cadmium (ppm)	15
		Hexavalent-Chromium (ppm)	15
		PBB (ppm)	ND***
		PBDE (ppm)	ND
	<b>Green</b>	Bromine (ppm)	ND
		Antimony (ppm)	ND
<b>Process Data</b>		MSL	3
		Max Solder Peak Temp (Reflow) C°	245
		Max Solder Peak Duration (Reflow) Seconds	40
		Max Solder Peak Temp (Wave) C°	Not Applicable
		Max Solder Peak Duration (Wave) Seconds	Not Applicable
		Confirm IPC/JEDEC J-STD-020C (without any limitations) (JULY 2004)	Yes
		Non Magnetic Component	Yes
<b>EOL Status</b>		Recommended for new designs. No EOL planned.	
<b>Document Rev</b>		1.1 2/8/2006	

\* R = RoHS compliant, G = Green compliant (RoHS and Sb/Br-free)  
 x (lower case) = any number from 0-9  
 X (upper case) = any letter from A-Z

\*\* Minimum 1 hour annealing bake @ 150°C within 24 hours of Sn Matte plating process to eliminate whiskering

\*\*\* ND = Non-Detectable